Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS:**

1. **-VIN**
2. **-VOUT**
3. **GND**

**.043”**

**2 1**

**3**

**5v**

**.043”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004 X .004” min.**

**Backside Potential: VIN**

**APPROVED BY: DK DIE SIZE .043 X .043” DATE: 11/14/22**

**MFG: SILICON SUPPLIES THICKNESS: .011” P/N: 79L05AC**

**DG 10.1.2**

#### Rev B, 7/19/02